

Application No. 10/664,755

NWAV 1002-2

In the Specification:

Please amend paragraph [0001] as follows:

[0001] The present application is a continuation-in-part of co-pending U.S. Patent Application No. 10/288,719, entitled METHOD AND APPARATUS FOR CUTTING DEVICES FROM CONDUCTIVE SUBSTRATES SECURED DURING CUTTING BY VACUUM PRESSURE, filed 5 November 2002 (now Patent 6,806,544) which is incorporated by reference as if fully set forth herein; and

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